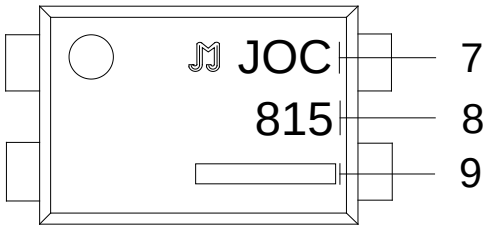
Isolation Voltage	V_{iso}	5000	Vrms
Operating Temperature	T_{opr}	-55~+110	
Storage Temperature	T_{stg}	-55~+125	
Soldering Temperature	T_{sol}	260	

NOTE1. 100μs pulse, 100Hz frequency

ORDERING AND MARKING INFORMATION

MARKING INFORMATION	
	7 : Company Abbr. 8 : Part Number & Rank 9 : Production Information Code
Packing Quantity	

Option Quan002 Tw

JOC815

FIG.7: Normalized Current Transfer Ratio vs. Ambient Temperature

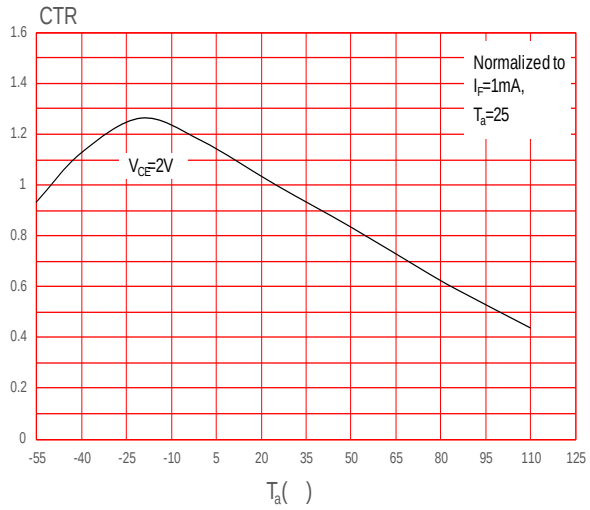


FIG.8: Normalized Collector-emitter Saturation Voltage vs. Ambient Temperature

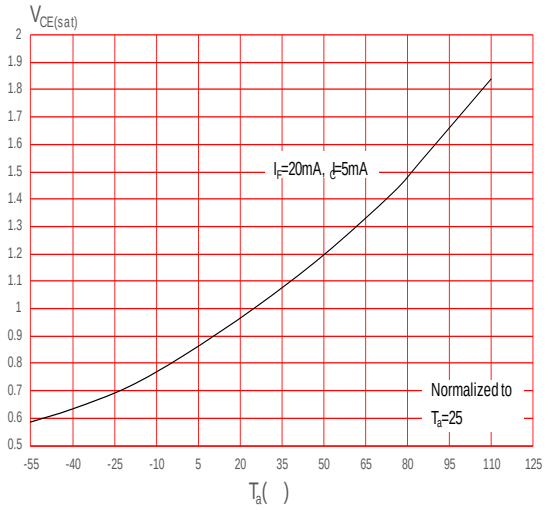


FIG.9: Response Time vs. Load Resistance

FIG.10: Frequency Response

Test Circuits

FIG.11: Test Circuits of Response Time

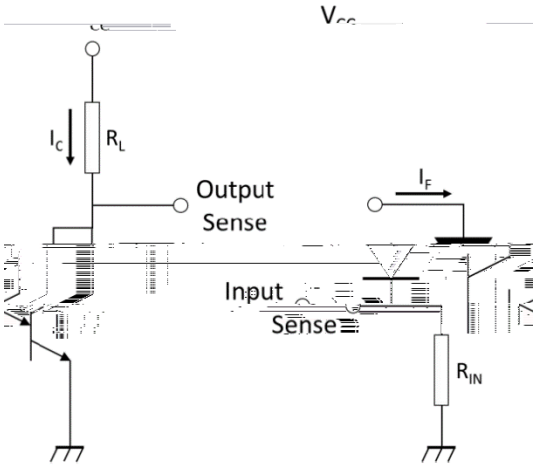
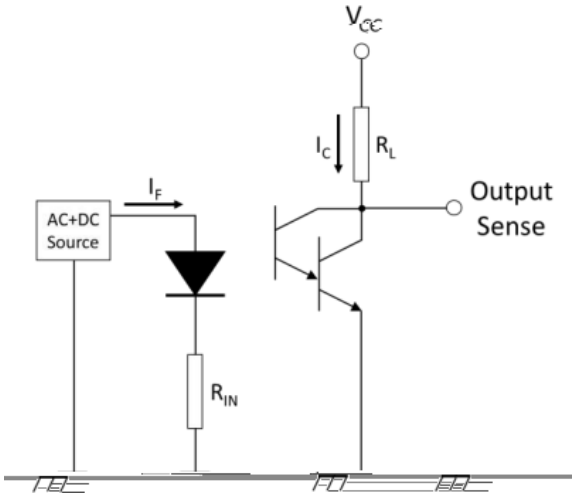


FIG.12: Curves of Response Time

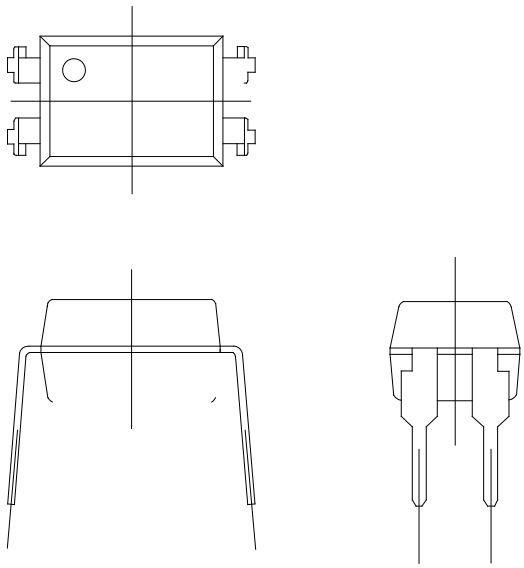


FIG.13: Test Circuits of Frequency Response

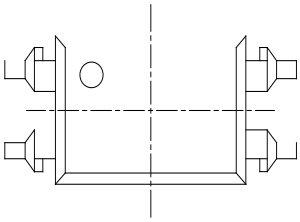


Package Dimension (Unit: mm Å

Standard DIP Type:

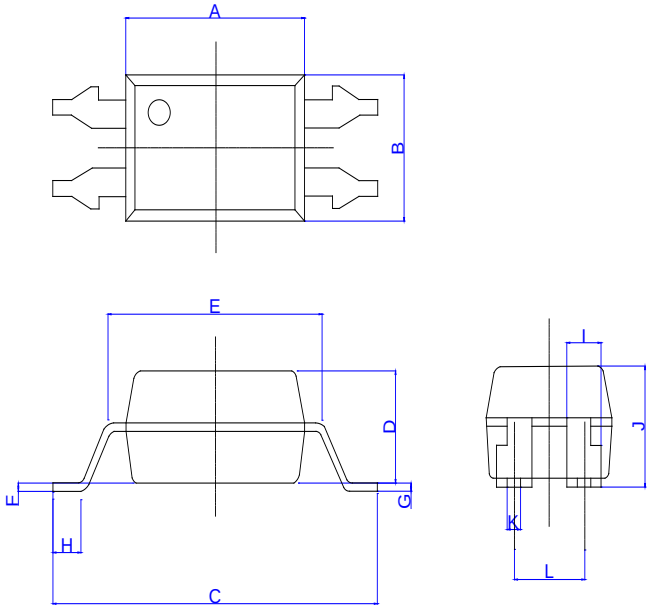


Option S Type:





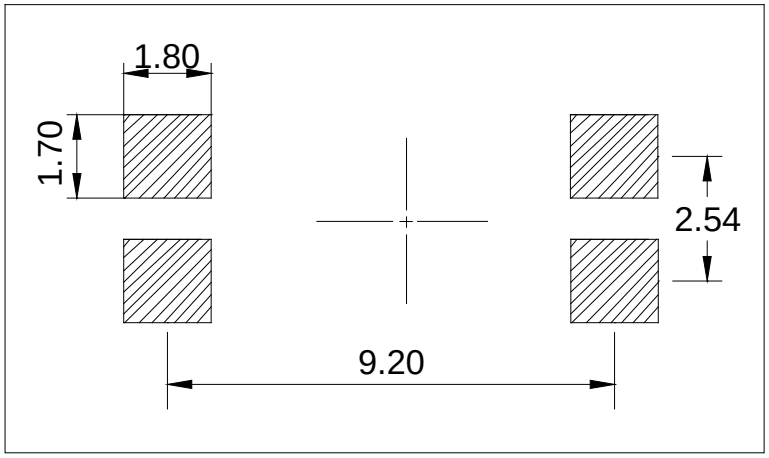
Option SLM Type:



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.30		6.70	0.248		0.264
B	4.38		4.78	0.172		0.188
C	11.60		12.10	0.457		0.476
D	3.30		3.70	0.130		0.146
E	7.32		7.92	0.288		0.312
F	0.00		0.30	0.000		0.012
G	0.20		0.30	0.008		0.012
H	0.50		0.90	0.020		0.035
I	1.15		1.35	0.045		0.053
J	3.45		3.85	0.136		0.152
K	0.45		0.55	0.018		0.022
L	2.34		2.74	0.092		0.108

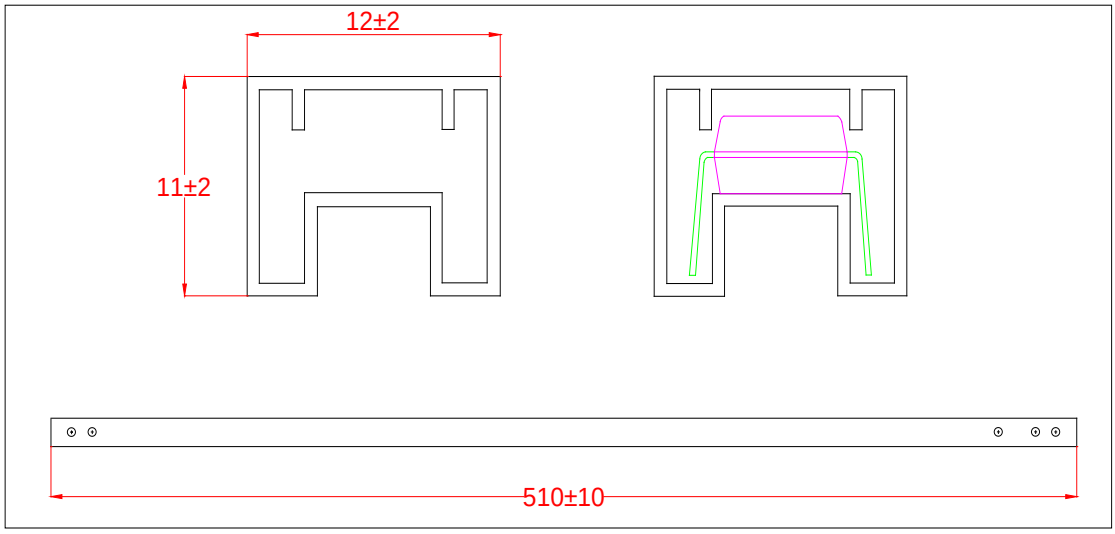
RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

Option S

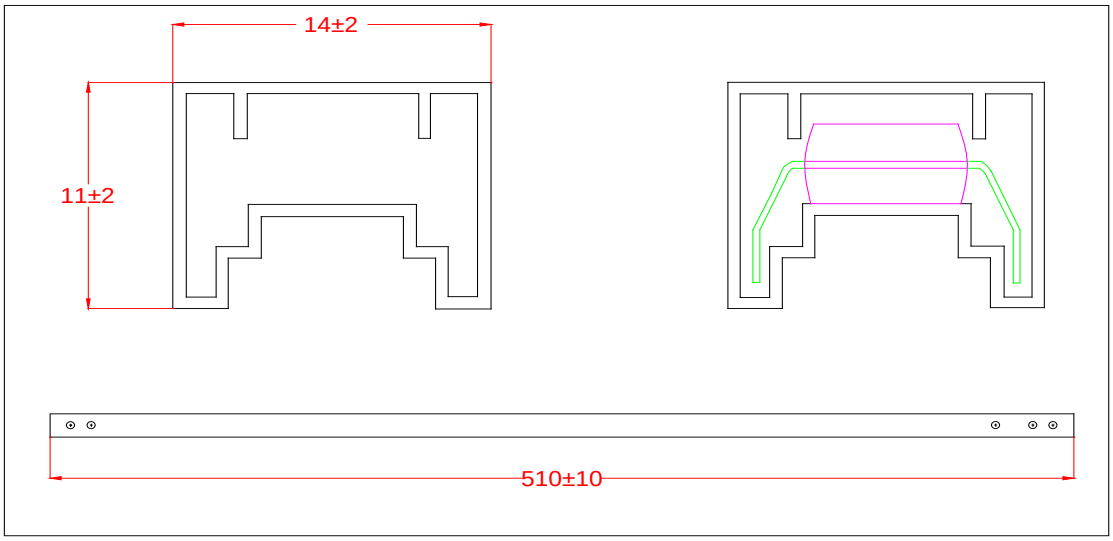


TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

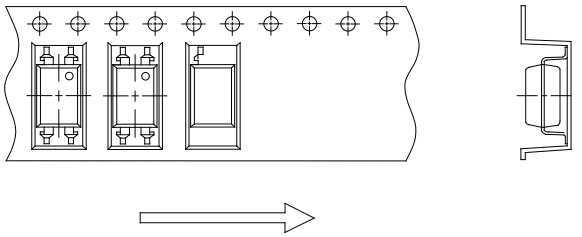
Standard DIP



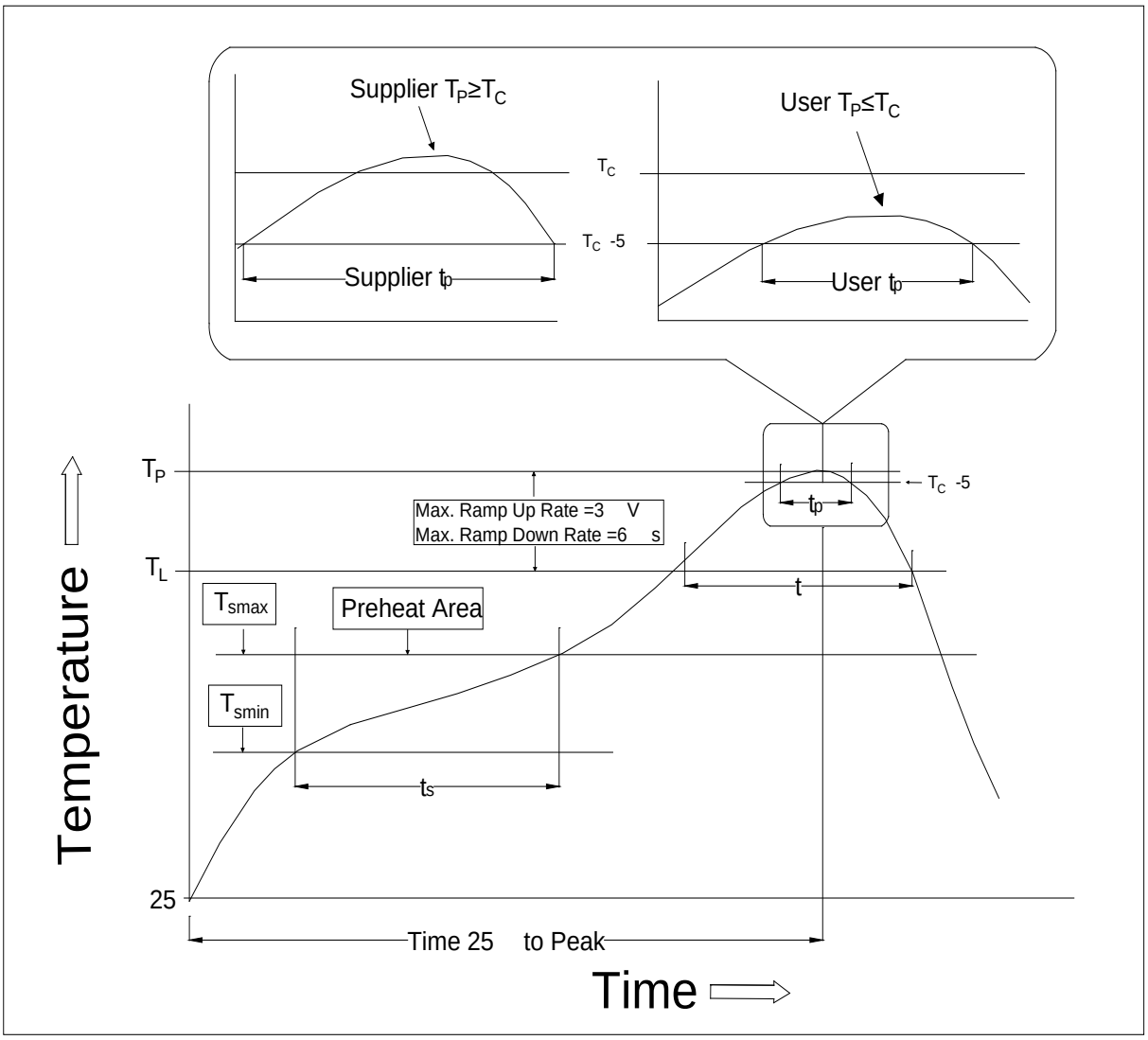
Option M



CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

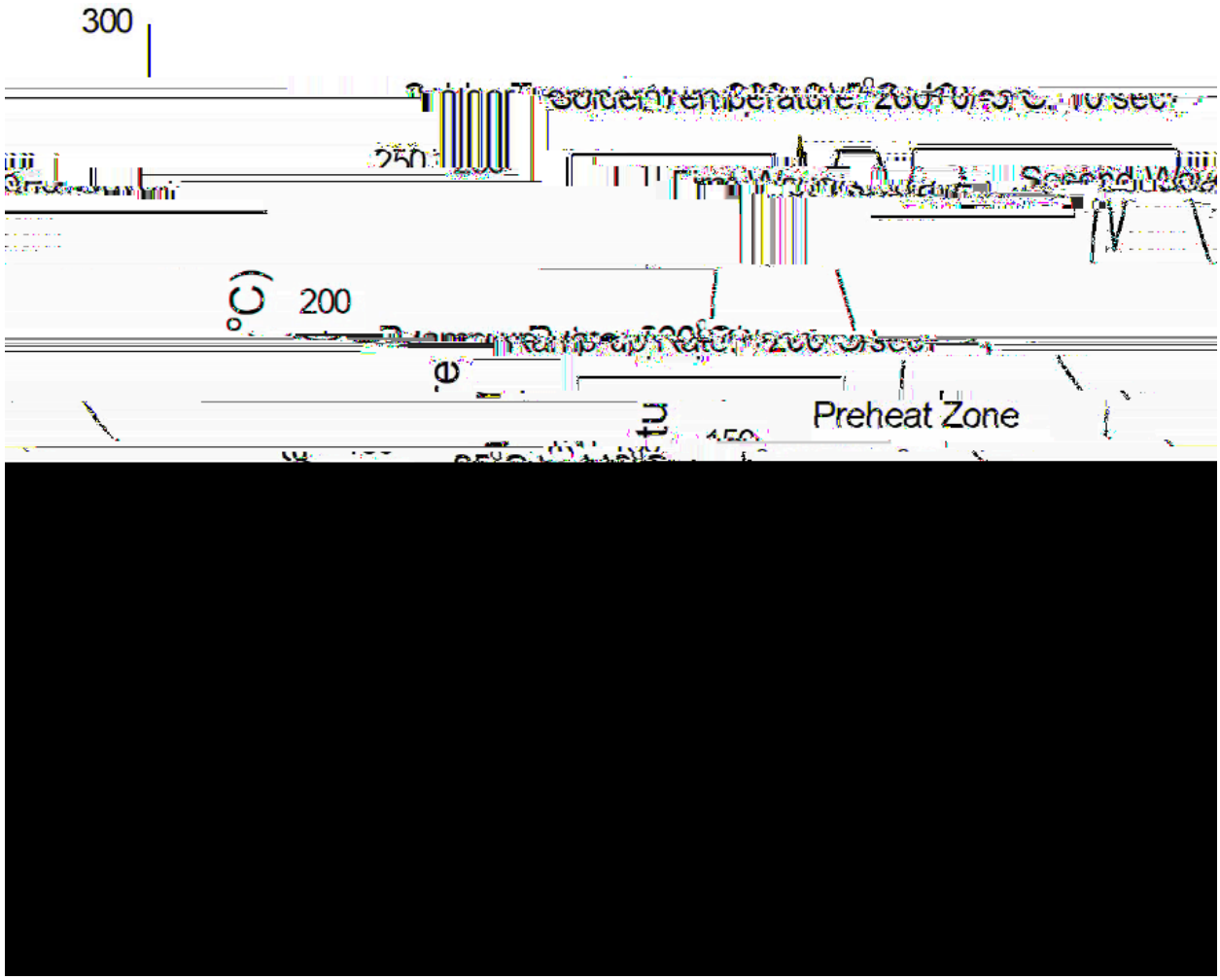


REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150
Temperature Max. (Tsmax)	150	200
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3 / second max.	3 / second max.
Liquidus Temperature (TL)	183	217
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (tP) within 5 of 260	10 seconds	10 seconds
Ramp-down Rate (TP to TL)	3-6 / second	3-6 / second
Time 25 to Peak Temperature	6 minutes max.	8 minutes max.

WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON	
Soldering Temperature	360 5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1

Information furnished in this document is believed to be accurate and reliable. However, Jiangsu JieJie Microelectronics Co., Ltd. assumes no responsibility for the consequences of use without consideration for such information nor use beyond it. Information mentioned in this document is subject to change without notice, apart from that when an agreement is signed, Jiangsu JieJie complies with the agreement.

Products and information provided in this document have no infringement of patents. Jiangsu JieJie assumes no responsibility for any infringement of other rights of third parties which may result from the use of such products and information. This document supersedes and replaces all information previously supplied.

is a registered trademark of Jiangsu JieJie Microelectronics Co., Ltd.

Copyright © 2026 Jiangsu JieJie Microelectronics Co., Ltd. All rights reserved.